

IN THE ABSTRACT:

Please amend the abstract as follows:

An electrical contact for use with a semiconductor device, a carrier, a probe card, or another substrate includes ~~a stereolithographically fabricated portion, which may comprise a plurality of at least partially superimposed, contiguous, mutually adhered layers. The electrical contact may include a dielectric core and a conductive coating on at least a portion thereof.~~ Alternatively, an electrical contact may include a plurality of adjacent, mutually adhered regions comprising, or it may be completely formed from conductive material. The electrical contact may be rigid or flexible and resilient. Protective structures for use with flexible resilient contacts prevent deformation of such contacts beyond their elastic limits. ~~Probe cards are also disclosed, as are methods for fabricating the electrical contacts, protective structures, and probe cards.~~